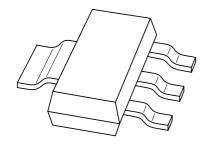
### **DISCRETE SEMICONDUCTORS**

# DATA SHEET



# BSP130 N-channel enhancement mode vertical D-MOS transistor

Product specification Supersedes data of 1997 Jun 23 2001 Dec 11





### N-channel enhancement mode vertical D-MOS transistor

**BSP130** 

#### **FEATURES**

- Direct interface to C-MOS, TTL, etc.
- High-speed switching
- No secondary breakdown.

#### **APPLICATIONS**

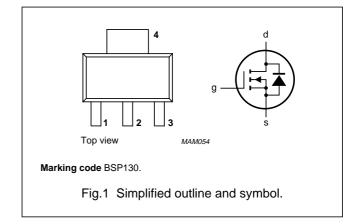
- Line current interruptor in telephone sets
- Relay, high-speed and line transformer drivers.

#### DESCRIPTION

N-channel enhancement mode vertical D-MOS transistor in a SOT223 package.

#### **PINNING - SOT223**

| PIN | DESCRIPTION |
|-----|-------------|
| 1   | gate        |
| 2   | drain       |
| 3   | source      |
| 4   | drain       |



### **QUICK REFERENCE DATA**

| SYMBOL            | PARAMETER                        | CONDITIONS                                    | MIN. | MAX. | UNIT |
|-------------------|----------------------------------|---|------|------|------|
| V <sub>DS</sub>   | drain-source voltage (DC)        |   | _    | 300  | V    |
| I <sub>D</sub>    | drain current (DC)               |   | _    | 350  | mA   |
| P <sub>tot</sub>  | total power dissipation          | T <sub>amb</sub> ≤ 25 °C                      | _    | 1.5  | W    |
| V <sub>GSO</sub>  | gate-source voltage              | open drain                                    | _    | ±20  | V    |
| R <sub>DSon</sub> | drain-source on-state resistance | $I_D = 250 \text{ mA}; V_{GS} = 10 \text{ V}$ | _    | 6    | Ω    |
| $V_{GSoff}$       | gate-source cut-off voltage      | $I_D = 1 \text{ mA}; V_{DS} = V_{GS}$         | 0.8  | 2    | V    |

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

| SYMBOL           | PARAMETER                 | CONDITIONS                       | MIN.       | MAX. | UNIT |
|------------------|---------------------------|----------------------------------|------------|------|------|
| V <sub>DS</sub>  | drain-source voltage (DC) |                                  | _          | 300  | V    |
| $V_{GSO}$        | gate-source voltage (DC)  | open drain                       | _          | ±20  | V    |
| I <sub>D</sub>   | drain current (DC)        |                                  | _          | 350  | mA   |
| I <sub>DM</sub>  | peak drain current        |                                  | _          | 1.4  | Α    |
| P <sub>tot</sub> | total power dissipation   | T <sub>amb</sub> ≤ 25 °C; note 1 | _          | 1.5  | W    |
| T <sub>stg</sub> | storage temperature       |                                  | <b>-55</b> | +150 | °C   |
| Tj               | junction temperature      |                                  | _          | 150  | °C   |

#### Note

1. Device mounted on an epoxy printed-circuit board, 40 x 40 x 1.5 mm, mounting pad for the drain tab minimum 6 cm<sup>2</sup>.

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### THERMAL CHARACTERISTICS

| SYMBOL              | PARAMETER   | VALUE | UNIT |
|---------------------|---|-------|------|
| R <sub>th j-a</sub> | thermal resistance from junction to ambient; note 1 | 83.3  | K/W  |

#### Note

1. Device mounted on an epoxy printed-circuit board, 40 x 40 x 1.5 mm, mounting pad for the drain tab minimum 6 cm<sup>2</sup>.

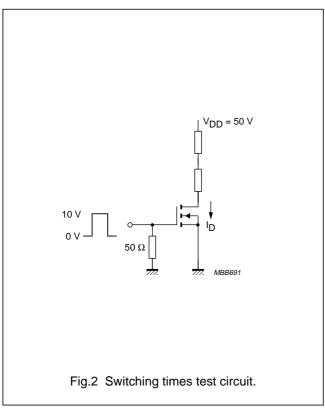
### STATIC CHARACTERISTICS

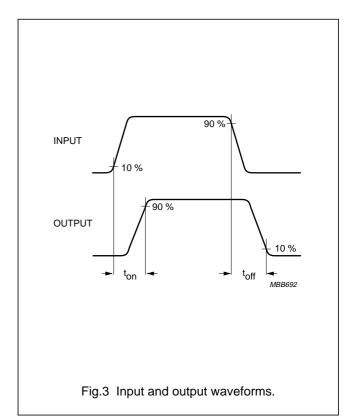
 $T_i = 25$  °C unless otherwise specified.

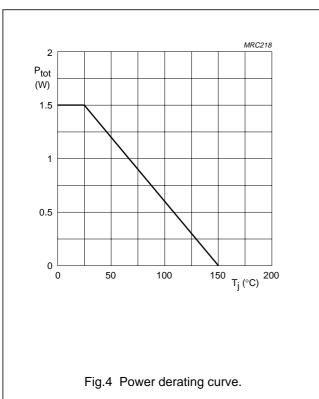
| SYMBOL               | PARAMETER                        | CONDITIONS  | MIN. | TYP. | MAX. | UNIT |
|----------------------|----------------------------------|---|------|------|------|------|
| V <sub>(BR)DSS</sub> | drain-source breakdown voltage   | $I_D = 10 \mu\text{A};  V_{GS} = 0$   | 300  | _    | _    | V    |
| I <sub>GSS</sub>     | gate-source leakage current      | $V_{GS} = \pm 20 \text{ V}; V_{DS} = 0$   | _    | _    | ±100 | nA   |
| V <sub>GSth</sub>    | gate-source threshold voltage    | $I_D = 1 \text{ mA}; V_{DS} = V_{GS}$   | 0.8  | _    | 2    | V    |
| R <sub>DSon</sub>    | drain-source on-state resistance | $I_D = 20 \text{ mA}; V_{GS} = 2.4 \text{ V}$   | _    | 4.8  | 10   | Ω    |
|                      |                                  | $I_D = 250 \text{ mA}; V_{GS} = 10 \text{ V}$   | _    | 3.7  | 6    | Ω    |
| I <sub>DSS</sub>     | drain-source leakage current     | V <sub>DS</sub> = 240 V; V <sub>GS</sub> = 0  | _    | _    | 100  | nA   |
| Y <sub>fs</sub>      | transfer admittance              | I <sub>D</sub> = 250 mA; V <sub>DS</sub> = 25 V   | 200  | 690  | _    | mS   |
| C <sub>iss</sub>     | input capacitance                | V <sub>DS</sub> = 25 V; V <sub>GS</sub> = 0; f = 1 MHz                                  | _    | 100  | 120  | pF   |
| C <sub>oss</sub>     | output capacitance               | V <sub>DS</sub> = 25 V; V <sub>GS</sub> = 0; f = 1 MHz                                  | _    | 21   | 30   | pF   |
| C <sub>rss</sub>     | feedback capacitance             | V <sub>DS</sub> = 25 V; V <sub>GS</sub> = 0; f = 1 MHz                                  | _    | 10   | 15   | pF   |
| Switching tir        | nes (see Figs 2 and 3)           |   | •    | _    |      |      |
| t <sub>on</sub>      | turn-on time                     | $I_D = 250 \text{ mA}; V_{DD} = 50 \text{ V};$<br>$V_{GS} = 0 \text{ to } 10 \text{ V}$ | _    | 6    | 10   | ns   |
| t <sub>off</sub>     | turn-off time                    | $I_D = 250 \text{ mA}; V_{DD} = 50 \text{ V};$<br>$V_{GS} = 10 \text{ to } 0 \text{ V}$ | _    | 46   | 60   | ns   |

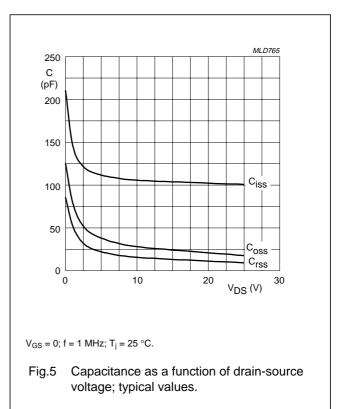
### N-channel enhancement mode vertical D-MOS transistor

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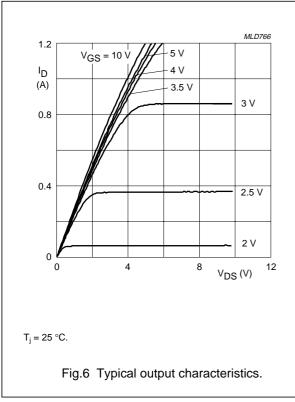


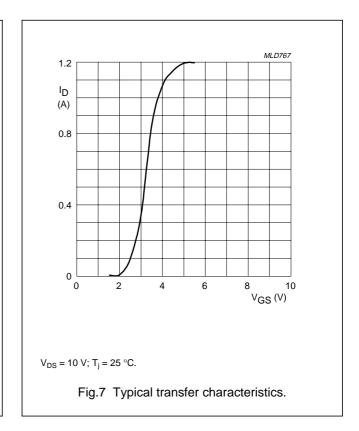


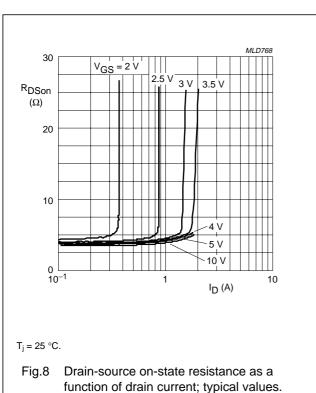


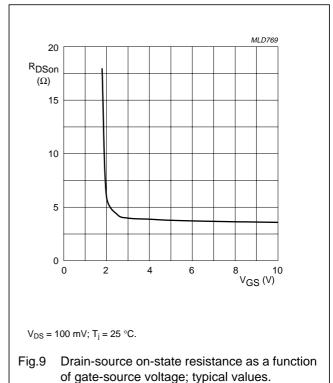
### N-channel enhancement mode vertical D-MOS transistor

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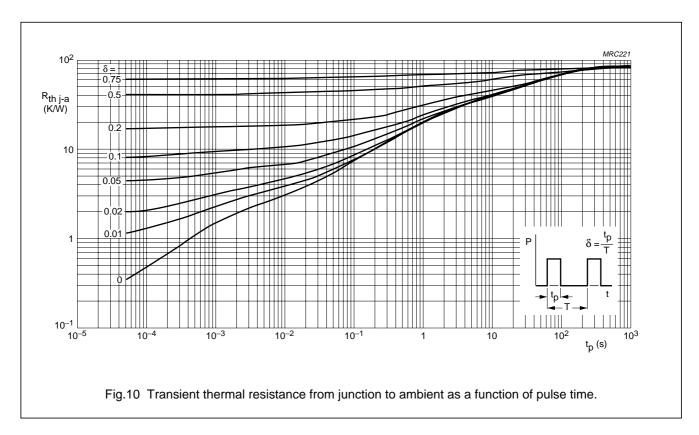


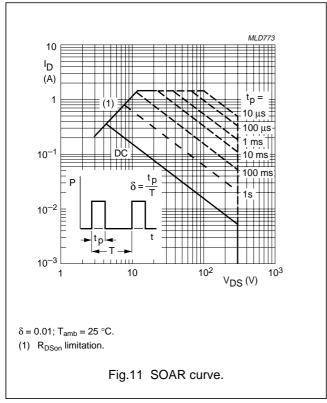




### N-channel enhancement mode vertical D-MOS transistor

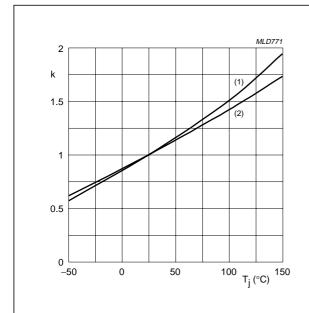
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### N-channel enhancement mode vertical D-MOS transistor

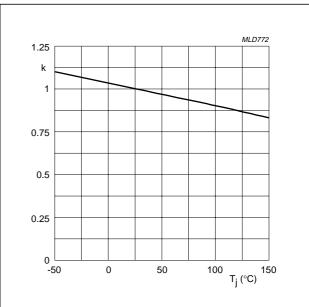
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$$k = \frac{R_{DS(on)} \text{ at } T_j}{R_{DS(on)} \text{at } 25 \text{ °C}}$$

Typical R<sub>DSon</sub>; (1)  $I_D = 250$  mA;  $V_{GS} = 10$  V. (2)  $I_D = 20$  mA;  $V_{GS} = 2.4$  V.

Fig.12 Temperature coefficient of drain-source on-state resistance; typical values.



$$k = \frac{V_{GS(th)} \text{ at } T_j}{V_{GS(th)} \text{ at 25 } ^{\circ}C}$$

Typical V<sub>GSth</sub> at 1 mA.

Fig.13 Temperature coefficient of gate-source threshold voltage; typical values.

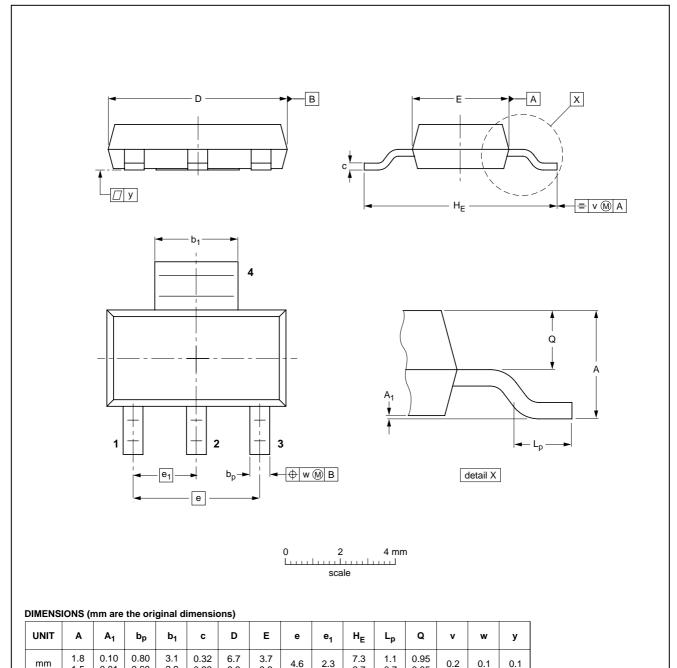
### N-channel enhancement mode vertical D-MOS transistor

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### **PACKAGE OUTLINE**

Plastic surface mounted package; collector pad for good heat transfer; 4 leads

**SOT223** 



| OUTLINE | REFERENCES |       |       | EUROPEAN | ISSUE DATE |                                 |
|---------|------------|-------|-------|----------|------------|---------------------------------|
| VERSION | IEC        | JEDEC | EIAJ  |          | PROJECTION | ISSUE DATE                      |
| SOT223  |            |       | SC-73 |          |            | <del>97-02-28</del><br>99-09-13 |

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1.5

0.01

0.60

2.9

0.22

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#### **DATA SHEET STATUS**

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|----------------------|----------------------------------|--|
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## N-channel enhancement mode vertical D-MOS transistor

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**NOTES** 

## N-channel enhancement mode vertical D-MOS transistor

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**NOTES** 

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